

April 1995

8-Bit, 125 MSPS Flash A/D Converter

Features

- Differential Linearity Error ± 0.5 LSB (Typ) or Less
- Integral Linearity Error ± 0.5 LSB (Typ) or Less
- Built-In Integral Linearity Compensation Circuit
- Ultra High Speed Operation with Maximum Conversion Rate of 125 MSPS (Min)
- Low Input Capacitance 18pF (Typ)
- Wide Analog Input Bandwidth 200MHz (Min. for Full-Scale Input)
- Single Power Supply -5.2V
- Low Power Consumption 870mW (Typ)
- Low Error Rate
- Operable at 50% Clock Duty Cycle
- Capable of Driving 50 Ω Loads

Applications

- Video Digitizing
- HDTV (High Definition TV)
- Direct RF Down-Conversion
- Communication Systems
- Radar Systems
- Digital Oscilloscopes

Description

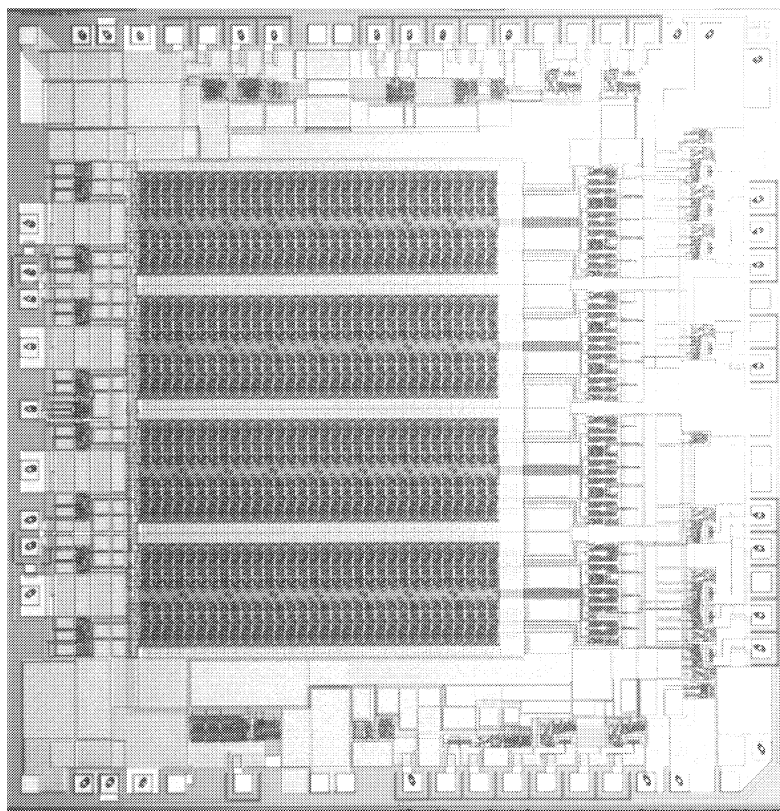
The HI1396Y is an 8-bit ultra high speed flash analog-to-digital converter IC capable of digitizing analog signals at the maximum rate of 125MSPS. The digital I/O levels of the converter are compatible with ECL 100K/10KH/10K.

The HI1396Y is available for Commercial and Industrial applications and is supplied in die form.

Ordering Information

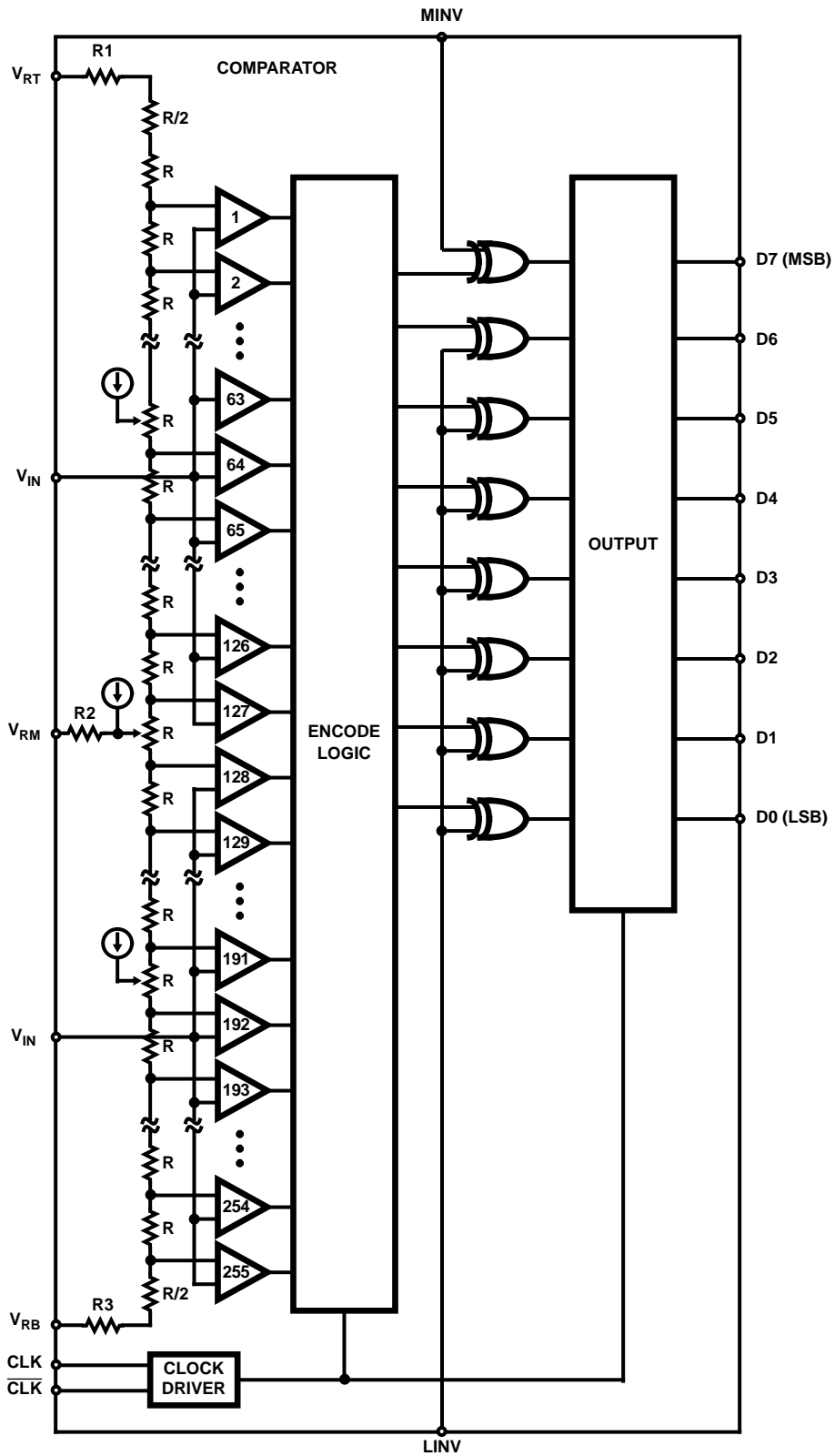
PART NUMBER	TEMPERATURE	PACKAGE
HI1396Y	+25°C	Die
<ul style="list-style-type: none"> • All performance parameters are for packaged devices when supplied by Harris. 		

Die Metallization Layer



PIN 66 PIN 1

Functional Block Diagram



Specifications HI1396Y

Absolute Maximum Ratings $T_A = +25^\circ\text{C}$

Supply Voltage (V_{EE} , DV_{EE})-7V	V_{RM} Pin Input Current (I_{VRM})-3mA to +3mA
Analog Input Voltage (V_{IN})-2.7V to +0.5V	Digital Output Current (ID0 to ID7)-30mA to 0mA
Reference Input Voltage		Storage Temperature Range (T_{STG})-65°C to +150°C
V_{RT} , V_{RB} , V_{RM}-2.7V to +0.5V	Maximum Junction Temperature	
$ V_{RT}-V_{RB} $2.5V	HI1396YJP+150°C
Digital Input Voltage			
CLK, $\overline{\text{CLK}}$, MINV, LINV-4V to +0.5V		
$ \text{CLK}-\overline{\text{CLK}} $2.7V		

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Operating Conditions (Note 1)

Supply Voltage		Analog Input Voltage, V_{IN} V_{RB} to V_{RT}
V_{EE} , DV_{EE}-5.5V to -4.95V	Pulse Width of Clock	
$V_{EE} - DV_{EE}$-0.05V to 0.05V	TPW14.0ns Min.
AGND - DGND-0.05V to 0.05V	TPW04.0ns Min.
Reference Input Voltage			
V_{RT}-0.1V to 0.1V		
V_{RB}-2.2V to -1.8V		

Electrical Specifications $T_A = +25^\circ\text{C}$, $V_{EE} = DV_{EE} = -5.2\text{V}$, $V_{RT} = 0\text{V}$, $V_{RB} = -2\text{V}$

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Differential Linearity Error (DNL)		-0.5	0.5	LSB
Integral Linearity Error (INL)		-0.5	0.5	LSB
Resolution		8	-	Bits
Input Bias Current, I_{IN}	$V_{IN} = -1.0\text{V}$	0	300	μA
Analog Input Resistance, R_{IN}	$V_{IN} = -1.0\text{V}$	60	500	$\text{k}\Omega$
Resister-String Current, I_{REF}		-22	-16	mA
Reference Voltage, V_{RM}		-1.02	-0.98	V
Digital Input Current HI, I_{IH}	$H_i = -0.8\text{V}$	0	50	μA
Digital Input Current LO, I_{IL}	$L_o = -1.6\text{V}$	-50	50	μA
$\overline{\text{CLK}}$ Open Voltage, V_{OPN}	$\overline{\text{CLK}} = \text{Open}$	-1.4	-1.2	V
Leakage (1) D0 to D7, V_{LEAK}	$I = -10\mu\text{A}$	-0.8	-0.4	V
Leakage (2) D0 to D7, V_{IN} , LINV, MINV, CLK, $\overline{\text{CLK}}$, I_{LEAK}	$V = 0.3\text{V}$	-1.0	1.0	μA
Digital Output Voltage HI, V_{OH}	220 Ω to -5.2V	-1.095	-0.6	V
Digital Output Voltage LO, V_{OL}	220 Ω to -5.2V	-2	-1.64	V
Supply Current, I_{EE}		-220	-105	mA

Timing Diagram

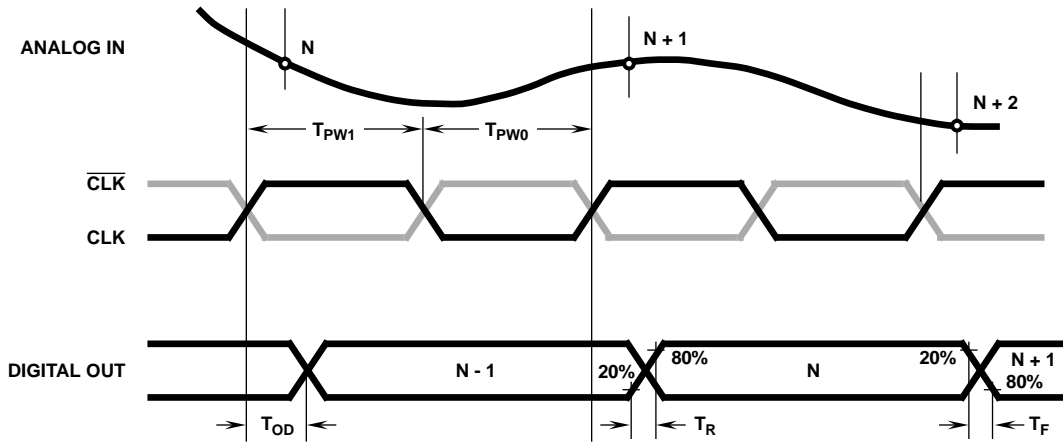


FIGURE 1.

Pad Descriptions

PAD NUMBER	SYMBOL	I/O	STANDARD VOLTAGE LEVEL	EQUIVALENT CIRCUIT	DESCRIPTION
50, 53, 55, 58	AGND	-	0V		Analog GND. Used as GND for input buffers and latches of comparators. Isolated from DGND.
47, 48, 60, 61	AV _{EE}	-	-5.2V		Analog V _{EE} -5.2V (Typ.). Internally connected to DV _{EE} (Resistance: 4Ω to 6Ω). Bypass with 0.1μF to AGND.
39	CLK	I	ECL		CLK Input
38	$\overline{\text{CLK}}$				Input complementary to CLK. When left open pulled down to -1.3V. Device is operable without CLK input, but use of complementary inputs of CLK and $\overline{\text{CLK}}$ is recommended to obtain stable high speed operation.
9, 11, 27, 29	DGND	-	0V		Digital GND.
8, 30	DV _{EE}	-	-5.2V		Digital V _{EE} . Internally connected to AV _{EE} (resistance: 4Ω to 6Ω). Bypass with 0.1μF to DGND

Pad Descriptions (Continued)

PAD NUMBER	SYMBOL	I/O	STANDARD VOLTAGE LEVEL	EQUIVALENT CIRCUIT	DESCRIPTION
12	D0	O	ECL		LSB of data outputs. External pull-down resistor is required.
13	D1				Data outputs. External pull-down resistors are required.
15	D2				
16	D3				
21	D4				
24	D5				
25	D6				
26	D7		MSB of data outputs. External pull-down resistor is required.		
1	LINV	I	ECL		Input for D0 (LSB) to D6 output polarity inversion (see A/D Output Code Table). Pulled low when left open.
35	MINV	I	ECL		Input for D7 (MSB) output polarity inversion (see A/D Output Code Table). Pulled low when left open.
51, 52, 56, 57	V_{IN}	I	V_{RT} to V_{RB}		Analog input pads. These two pads must be connected externally, since they are not internally connected.

Pad Descriptions (Continued)

PAD NUMBER	SYMBOL	I/O	STANDARD VOLTAGE LEVEL	EQUIVALENT CIRCUIT	DESCRIPTION
46	V_{RB}	I	-2V		Reference voltage (bottom). Typically -2V. Bypass with a 0.1 μ F and 10 μ F to AGND.
54	V_{RM}	I	$V_{RB}/2$		Reference voltage mid point. Can be used as a pad for integral linearity compensation. Reference voltage (top) typically 0V. When a voltage different from AGND is applied to this pad, bypass with a 0.1 μ F and 10 μ F to AGND.
62	V_{RT}	I	0V		Reference voltage (top) typically 0V. When a voltage different from AGND is applied to this pad, bypass with a 0.1 μ F and 10 μ F to AGND.
2 - 7, 10, 14, 17 - 20, 22, 23, 28, 31 - 34, 36, 37, 40 - 45, 49, 59, 63 - 66	NC	-	-		Unused pads. No internal connections have been made to these pads. Connecting them to AGND or DGND is recommended.

A/D OUTPUT CODE TABLE

V_{IN} (Note 1)	STEP	MINV 1, LINV 1		0, 1		1, 0		0, 0	
		D7	D0	D7	D0	D7	D0	D7	D0
0V	0	000	000	100	000	011	011	111	111
		000	000	100	000	011	011	111	111
		000	001	100	001	011	010	111	110
-1V	127	011	011	111	011	000	000	100	000
		100	000	000	000	111	011	011	111
		111	010	011	010	100	001	000	001
-2V	254	111	010	011	010	100	001	000	001
	255	111	011	011	011	100	000	000	000

NOTE:
1. $V_{RT} = 0V$, $V_{RB} = -2V$.

HI1396Y

Pad Coordinates

PAD COORDINATE 1

PAD NO.	PAD NAME	X [μm]	Y [μm]
1	LINV	2198.40	4490.40
2		2008.00	4490.40
3		1817.60	4490.40
4		1627.20	4490.40
5		1436.80	4490.40
6		1246.40	4490.40
7		1056.00	4490.40
8	DV _{EE}	865.60	4490.40
9	DGND	675.20	4490.40
10		388.80	4490.40
11	DGND	209.60	4311.20
12	D0	209.60	3730.40
13	D1	209.60	3540.00
14		209.60	3349.60
15	D2	209.60	3159.20
16	D3	209.60	2968.80
17		209.60	2778.40
18		209.60	2629.60
19		209.60	2458.40
20		209.60	2301.60
21	D4	209.60	2111.20
22		209.60	1920.80

PAD NO.	PAD NAME	X [μm]	Y [μm]
23		209.60	1730.40
24	D5	209.60	1540.00
25	D6	209.60	1349.60
26	D7	209.60	1159.20
27	DGND	209.60	588.00
28		209.60	362.40
29	DGND	484.80	215.20
30	DV _{EE}	675.20	215.20
31		865.60	215.20
32		1056.00	215.20
33		1246.40	215.20
34		1436.80	215.20
35	MINV	1627.20	215.20
36		1817.60	215.20
37		2008.00	215.20
38	$\overline{\text{CLK}}$	2198.40	215.20
39	CLK	2388.80	215.20
40		2579.20	215.20
41		2728.00	215.20
42		2974.40	215.20
43		3164.80	215.20
44		3355.20	215.20

PAD NO.	PAD NAME	X [μm]	Y [μm]
45		3545.60	215.20
46	V _{RB}	3736.00	215.20
47	AV _{EE}	3926.40	215.20
48	AV _{EE}	4075.20	215.20
49		4377.60	215.20
50	AGND	4377.60	1292.00
51	V _{IN}	4377.60	1570.40
52	V _{IN}	4377.60	1720.80
53	AGND	4377.60	1999.20
54	V _{RM}	4377.60	2352.80
55	AGND	4377.60	2698.40
56	V _{IN}	4377.60	2984.80
57	V _{IN}	4377.60	3135.20
58	AGND	4377.60	3413.60
59		4377.60	4490.40
60	AV _{EE}	4075.20	4490.40
61	AV _{EE}	3926.40	4490.40
62	V _{RT}	3736.00	4490.40
63		3545.60	4490.40
64		3164.80	4490.40
65		2728.00	4490.40
66		2579.20	4490.40

Pad Coordinates (Continued)

PAD COORDINATE 2

PAD NO.	PAD NAME	X [μm]	Y [μm]
1	LINV	2158.40	4450.40
2		1968.00	4450.40
3		1777.60	4450.40
4		1587.20	4450.40
5		1396.80	4450.40
6		1206.40	4450.40
7		1016.00	4450.40
8	DV _{EE}	825.60	4450.40
9	DGND	635.20	4450.40
10		348.80	4450.40
11	DGND	169.60	5271.20
12	D0	169.60	3690.40
13	D1	169.60	3500.00
14		169.60	3309.60
15	D2	169.60	3119.20
16	D3	169.60	2928.80
17		169.60	2738.40
18		169.60	2589.60
19		169.60	2418.40
20		169.60	2261.60
21	D4	169.60	2071.20
22		169.60	1880.80

PAD NO.	PAD NAME	X [μm]	Y [μm]
23		169.60	1690.40
24	D5	169.60	1500.00
25	D6	169.60	1309.60
26	D7	169.60	1119.20
27	DGND	169.60	548.00
28		169.60	322.40
29	DGND	444.80	175.20
30	DV _{EE}	635.20	175.20
31		825.60	175.20
32		1016.00	175.20
33		1206.40	175.20
34		1396.80	175.20
35	MINV	1587.20	175.20
36		1777.60	175.20
37		1968.00	175.20
38	$\overline{\text{CLK}}$	2158.40	175.20
39	CLK	2348.80	175.20
40		2539.20	175.20
41		2688.00	175.20
42		2934.40	175.20
43		3124.80	175.20
44		3315.20	175.20

PAD NO.	PAD NAME	X [μm]	Y [μm]
45		3505.60	175.20
46	V _{RB}	3696.00	175.20
47	AV _{EE}	3886.40	175.20
48	AV _{EE}	4035.20	175.20
49		4337.60	175.20
50	AGND	4337.60	1252.00
51	V _{IN}	4337.60	1530.40
52	V _{IN}	4337.60	1680.80
53	AGND	4337.60	1959.20
54	V _{RM}	4337.60	2312.80
55	AGND	4337.60	2658.40
56	V _{IN}	4337.60	2944.80
57	V _{IN}	4337.60	3095.20
58	AGND	4337.60	3373.60
59		4337.60	4450.40
60	AV _{EE}	4035.20	4450.40
61	AV _{EE}	3886.40	4450.40
62	V _{RT}	3696.00	4450.40
63		3505.60	4450.40
64		3124.80	4450.40
65		2688.00	4450.40
66		2539.20	4450.40

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